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PATENT ASSIGNMENT

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SUBMISSION TYPE:	NEW ASSIGNMENT
NATURE OF CONVEYANCE:	ASSIGNMENT

CONVEYING PARTY DATA

Name	Execution Date
Zhiqiang Wu	10/05/2012
Gwan Sin Chang	10/05/2012
Kuo-Cheng Ching	10/05/2012
Chun Chung Su	10/08/2012
Shi Ning Ju	10/05/2012

RECEIVING PARTY DATA

Name:	Taiwan Semiconductor Manufacturing Company, Ltd.
Street Address:	No. 8, Li-Hsin Rd. 6
Internal Address:	Science-Based Industrial Park
City:	Hsin-Chu
State/Country:	TAIWAN
Postal Code:	300-77

PROPERTY NUMBERS Total: 1

Property Type	Number
Application Number:	13631688

OP $40.00 13631688

CORRESPONDENCE DATA

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ATTORNEY DOCKET NUMBER:	24061.2263/2012-0631

NAME OF SUBMITTER:	David M. O'Dell

Total Attachments: 3
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Docket No.: 2012-0631 / 24061.2263
Customer No.: 42717

ASSIGNMENT

WHEREAS, we,

(1) Zhiqiang Wu of 9F-7, No. 1, Aikou 1st Street
Chubei, Hsinchu County, Taiwan, R.O.C.

(2) Gwan Sin Chang of 6F, No. 25, Lane 28, Sec. 1, Tiedao Road
Hsinchu City, Taiwan, R.O.C.

(3) Kuo-Cheng Ching of 5F, No. 8-3, Guangming 9th Road
Zhubei City, Hsinchu County 302, Taiwan, R.O.C.

(4) Chun Chung Su of 4F, No. 131, Huashun Street, Zhonghe District
New Taipei City 235, Taiwan, R.O.C.

(5) Shi Ning Ju of 10F, No. 306, Lane 1050, Minghu Road, East District
Hsinchu City 300, Taiwan, R.O.C.

have invented certain improvements in

SOURCE/DRAIN STACK STRESSOR FOR SEMICONDUCTOR DEVICE

for which we have filed an application for Letters Patent of the United States of America on September 28, 2012 as U.S. Serial No. 13/631,688 ; and

WHEREAS, Taiwan Semiconductor Manufacturing Company, Ltd., ("TSMC"), No. 8, Li-Hsin Rd. 6, Science-Based Industrial Park Hsin-Chu, Taiwan 300-77, Republic of China. is desirous of obtaining the entire right, title, and interest in, to and under the said invention and the said application in the United States of America and in any and all countries foreign thereto;

NOW, THEREFORE, good and valuable consideration, the receipt and sufficiency of which is hereby acknowledged, and other good and valuable consideration, we have sold, assigned, transferred and set over, and by these presents do hereby sell, assign, transfer and set over, unto the said TSMC, its successors, legal representatives, and assigns, the entire right, title, and interest in, to and under the said invention, and the said application, and all divisional, renewal, substitutional, and continuing applications thereof, and all Letters Patent of the United States of America which may be granted thereon and all reissues and extensions thereof, and all applications for Letters Patent which may be filed for said invention in any country or countries foreign to the United States of America, and all extensions, renewals, and reissues thereof, and all prior patents and patent applications from which a filing priority of the above-described patent application may be obtained, including the right to collect past damages; and we hereby authorize and request the Commissioner of Patents of the United States of America, and any official of any country or countries foreign to the United States of America, whose duty it is to issue patents on applications as aforesaid, to issue all Letters Patent for said invention to the said TSMC, its successors, legal representatives and assigns, in accordance with the terms of this instrument.

AND WE HEREBY covenant that we have full right to convey the entire interest herein assigned, and that we have not executed, and will not execute, any agreement in conflict herewith.

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AND WE HEREBY further covenant and agree that we will communicate to said TSMC, its successors, legal representatives and assigns, any facts known to us respecting said invention, and testify in any legal proceedings, sign all lawful papers, execute all divisional, renewal, substitutional, continuing, and reissue applications, make all rightful declarations and/or oaths and generally do everything possible to aid the said TSMC, its successors, legal representatives and assigns, to obtain and enforce proper patent protection for said invention in all countries.

Inventor Name: Zhiqiang Wu

Residence Address: 9F-7, No. 1, Aikou 1st Street
Chubei, Hsinchu County, Taiwan, R.O.C.

Dated: 10/5/2012

Inventor Signature

Inventor Name: Gwan Sin Chang

Residence Address: 6F, No. 25, Lane 28, Sec. 1, Tiedao Road
Hsinchu City, Taiwan, R.O.C.

Dated: 2012.10.05

Gwan Sin Chang
Inventor Signature

Inventor Name: Kuo-Cheng Ching

Residence Address: 5F, No. 8-3, Guangming 9th Road
Zhubei City, Hsinchu County 302, Taiwan, R.O.C.

Dated: 2012.10.05

Kuo-Cheng Ching
Inventor Signature

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Customer No.: 42717

Inventor Name: Chun Chung Su

Residence Address: 4F, No. 131, Huashun Street, Zhonghe District
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Dated: 2012, 10, 8

Chun Chung Su.
Inventor Signature

Inventor Name: Shi Ning Ju

Residence Address: 10F, No. 306, Lane 1050, Minghu Road, East District
Hsinchu City 300, Taiwan, R.O.C.

Dated: 2012. 10. 5

Shi Ning Ju
Inventor Signature
